



Session Title:	[WeA2] Advanced Cu and Mo CMP
Session Date:	November 13 (Wed.), 2024
Session Time:	14:10-15:45
Session Room:	Room A (Capri Room, 2F, Paradise Hotel Busan)
Session Chair:	Prof. Ho Jun Kim (Hanyang Univ., Korea)

[WeA2-1] [Invited] 14:10-14:40

Predicting Corrosion Inhibition Efficiency based on Charge Transfer Factor

Ganghyeok Kim, Ilhwa Hong, Donggeun Park, Wangil Song, Seokju Hong, Dongwon Kim, and Kangchun Lee (Kyonggi Univ., Korea)

[WeA2-2] [Invited] 14:40-15:05

Amorphous-Carbon-Layer CMP : Materials Properties and Solution

Jea-Gun Park (Hanyang Univ., Korea)

[WeA2-3] 15:05-15:25

Study on the Effect of Corrosion Inhibitors during Chemical Mechanical Planarization of Molybdenum

Daecheon Yang, Soekjoo Kim (Soulbrain Co., Ltd., Korea), Sangkyun Kim, Inkwon Kim, and Gayoung Kim (Samsung Electronics Co., Ltd., Korea)

[WeA2-4] 15:25-15:45

Advanced Additives for Enhanced Removal Rate and Defect Mitigation in Copper CMP Slurries

Junhyuk Kim and Seokjoo Kim (Soulbrain Co., Ltd., Korea)